

P-Channel 60 V (D-S) 175 °C MOSFET

| PRODUCT SUMMARY | | |
|---------------------|-------------------------------------|---------------------------------|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) ^c |
| - 60 | 0.0093 at V _{GS} = - 10 V | - 90 |
| | 0.0118 at V _{GS} = - 4.5 V | - 90 |

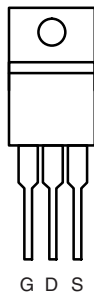
FEATURES

- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC


RoHS
COMPLIANT

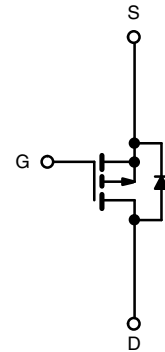
APPLICATIONS

- DC/DC Primary Switch

TO-220AB


Top View

Drain connected to Tab

Ordering Information: SUP90P06-09L-E3 (Lead (Pb)-free)


P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | |
|---|-----------------------------------|-----------------|------------------|
| Parameter | Symbol | Limit | Unit |
| Drain-Source Voltage | V _{DS} | - 60 | V |
| Gate-Source Voltage | V _{GS} | ± 20 | |
| Continuous Drain Current (T _J = 175 °C) ^c | T _C = 25 °C | I _D | - 90 |
| | T _C = 125 °C | | - 67 |
| Pulsed Drain Current | I _{DM} | - 200 | A |
| Avalanche Current | L = 0.1 mH | I _{AS} | - 65 |
| Single Pulse Avalanche Energy ^a | | E _{AS} | 211 |
| Power Dissipation | T _C = 25 °C | P _D | 250 ^b |
| | T _A = 25 °C | | 2.4 |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | - 55 to 175 | °C |

| THERMAL RESISTANCE RATINGS | | | |
|------------------------------|-------------------|-------|------|
| Parameter | Symbol | Limit | Unit |
| Junction-to-Ambient Free Air | R _{thJA} | 62 | °C/W |
| Junction-to-Case | R _{thJC} | 0.6 | |

Notes:

a. Duty cycle ≤ 1 %.

b. See SOA curve for voltage derating.

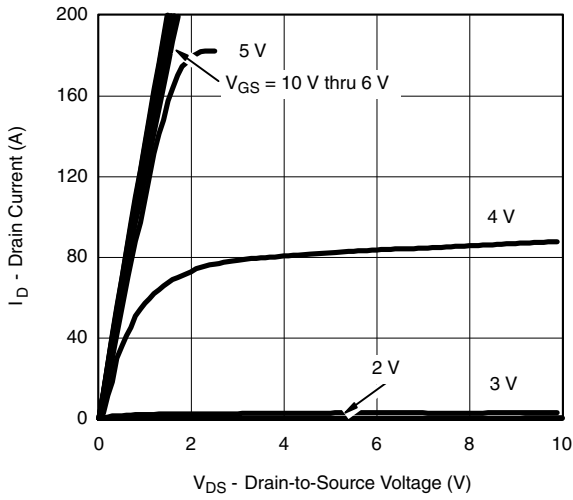
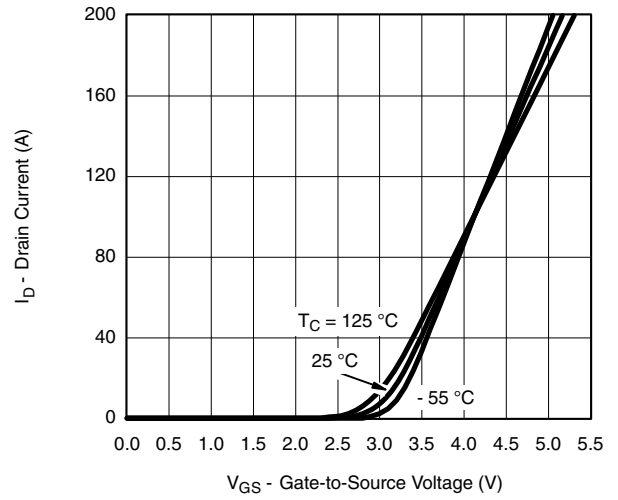
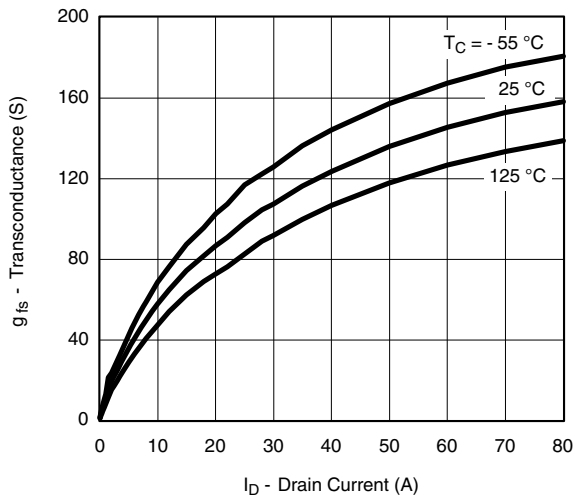
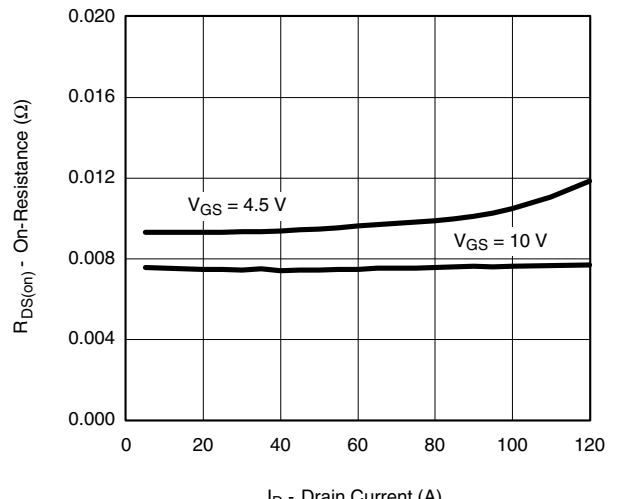
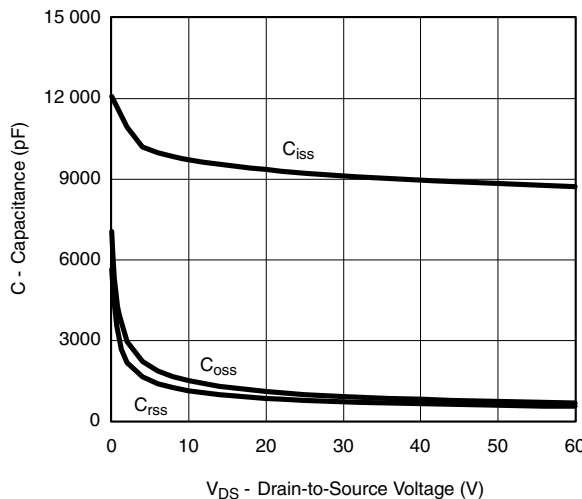
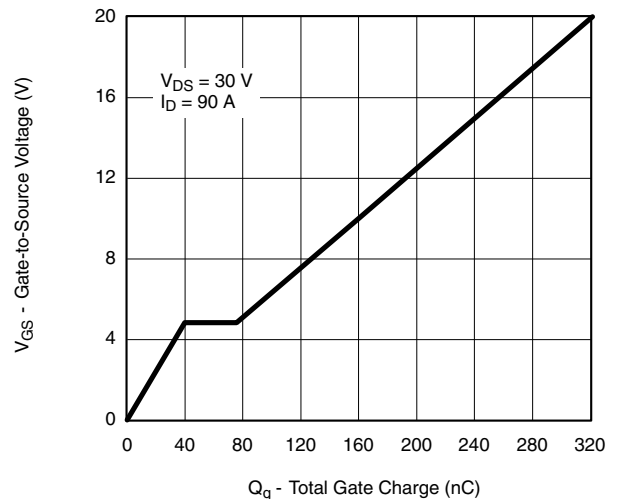
c. Limited by package.

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | |
|---|---------------|--|-------|--------|-----------|---------------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$ | - 60 | | | V |
| Gate-Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$ | - 1 | | - 3 | |
| Gate-Body Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}$ | | | - 1 | μA |
| | | $V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$ | | | - 50 | |
| | | $V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}, T_J = 175\text{ }^\circ\text{C}$ | | | - 250 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} = -5\text{ V}, V_{GS} = -10\text{ V}$ | - 120 | | | A |
| Drain-Source On-State Resistance ^a | $R_{DS(on)}$ | $V_{GS} = -10\text{ V}, I_D = -30\text{ A}$ | | 0.0074 | 0.0093 | Ω |
| | | $V_{GS} = -10\text{ V}, I_D = -30\text{ A}, T_J = 125\text{ }^\circ\text{C}$ | | | 0.0150 | |
| | | $V_{GS} = -10\text{ V}, I_D = -30\text{ A}, T_J = 175\text{ }^\circ\text{C}$ | | | 0.0190 | |
| | | $V_{GS} = -4.5\text{ V}, I_D = -20\text{ A}$ | | 0.0094 | 0.0118 | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = -15\text{ V}, I_D = -30\text{ A}$ | 20 | | | S |
| Dynamic^b | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = -25\text{ V}, f = 1\text{ MHz}$ | | 9200 | | pF |
| Output Capacitance | C_{oss} | | | 975 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 760 | | |
| Total Gate Charge ^c | Q_g | $V_{DS} = -30\text{ V}, V_{GS} = -10\text{ V}, I_D = -90\text{ A}$ | | 160 | 240 | nC |
| Gate-Source Charge ^c | Q_{gs} | | | 40 | | |
| Gate-Drain Charge ^c | Q_{gd} | | | 36 | | |
| Gate Resistance | R_g | $f = 1.0\text{ MHz}$ | | 3 | | Ω |
| Turn-On Delay Time ^c | $t_{d(on)}$ | $V_{DD} = -30\text{ V}, R_L = 0.33\text{ }\Omega$ $I_D \cong -90\text{ A}, V_{GEN} = -10\text{ V}, R_g = 2.5\text{ }\Omega$ | | 20 | 30 | ns |
| Rise Time ^c | t_r | | | 190 | 285 | |
| Turn-Off Delay Time ^c | $t_{d(off)}$ | | | 140 | 210 | |
| Fall Time ^c | t_f | | | 300 | 450 | |
| Source-Drain Diode Ratings and Characteristics ($T_C = 25\text{ }^\circ\text{C}$) ^b | | | | | | |
| Continuous Current | I_S | | | | - 90 | A |
| Pulsed Current | I_{SM} | | | | - 200 | |
| Forward Voltage ^a | V_{SD} | $I_F = -50\text{ A}, V_{GS} = 0\text{ V}$ | | - 1.0 | - 1.5 | V |
| Reverse Recovery Time | t_{rr} | $I_F = -50\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$ | | 60 | 90 | ns |
| Peak Reverse Recovery Current | $I_{RM(REC)}$ | | | - 3 | - 4.5 | A |
| Reverse Recovery Charge | Q_{rr} | | | | 0.09 | 0.2 |

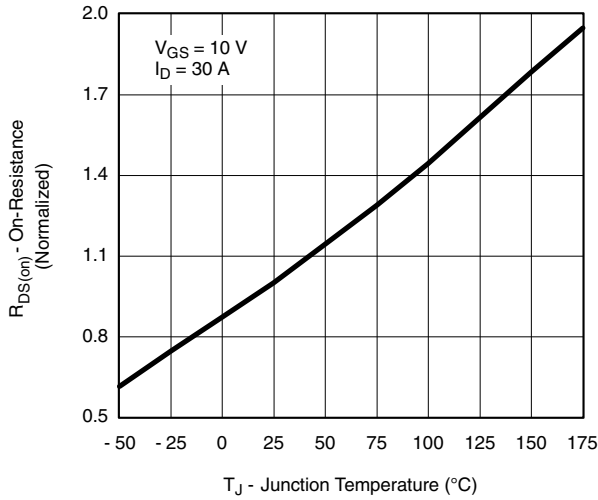
Notes:

- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

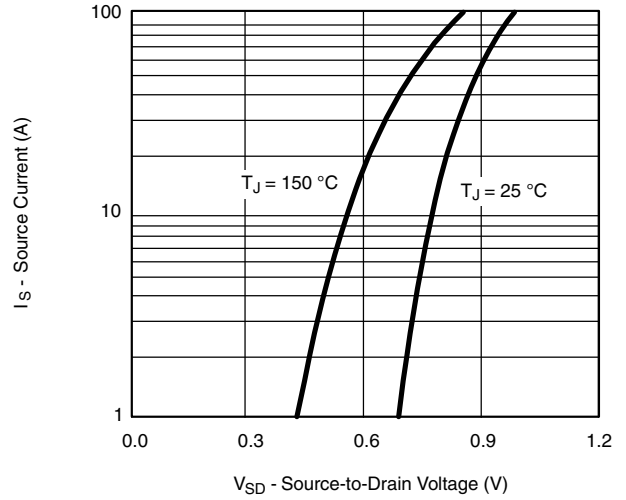
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

Transconductance

On-Resistance vs. Drain Current

Capacitance

Gate Charge

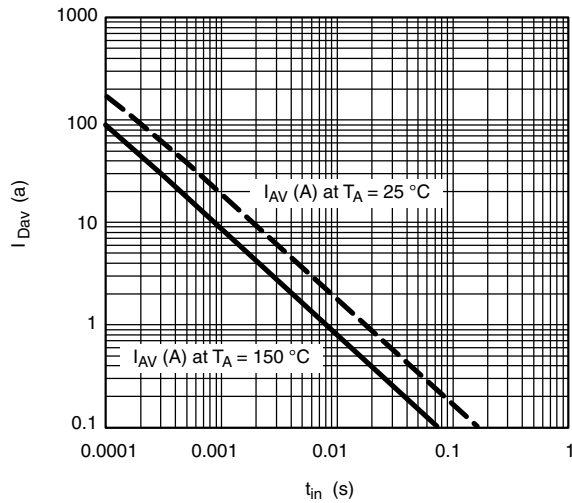
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



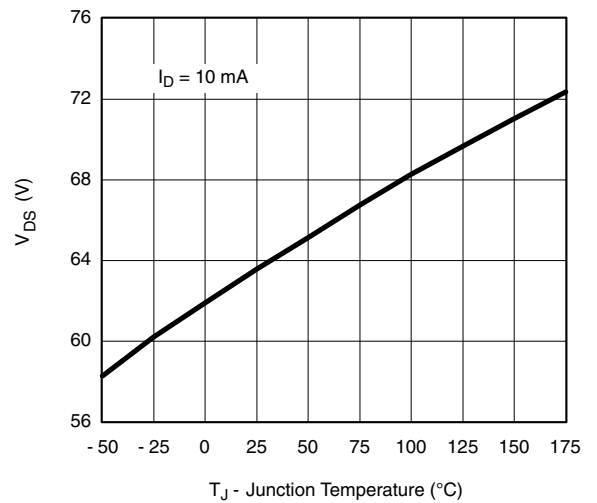
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage

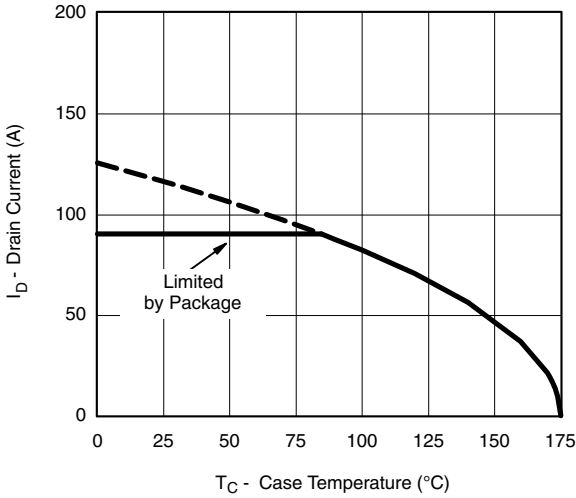


Avalanche Current vs. Time

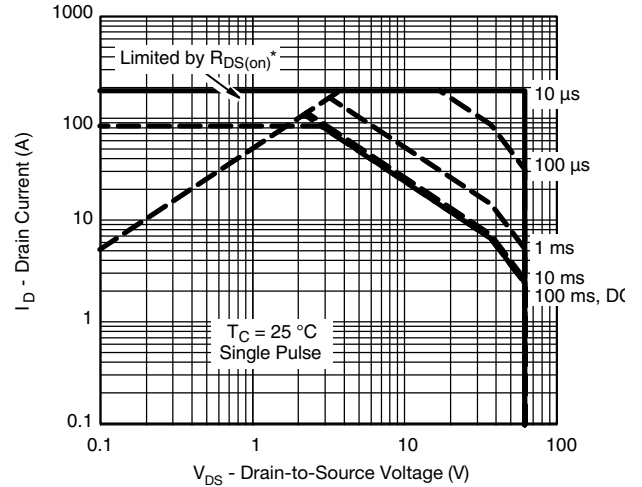


Drain Source Breakdown vs. Junction Temperature

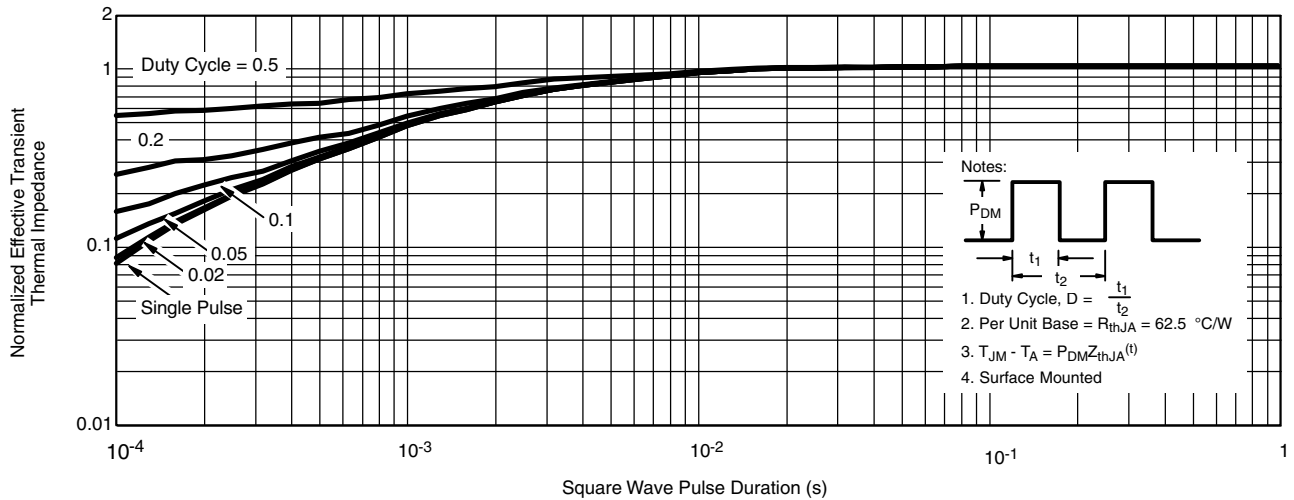
THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature



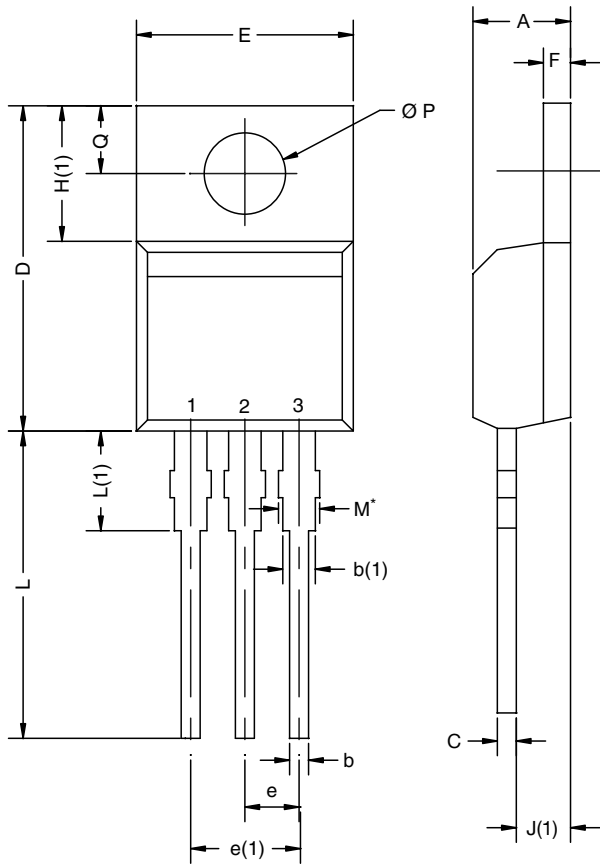
Safe Operating Area
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



Normalized Thermal Transient Impedance, Junction-to-Case

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TO-220AB

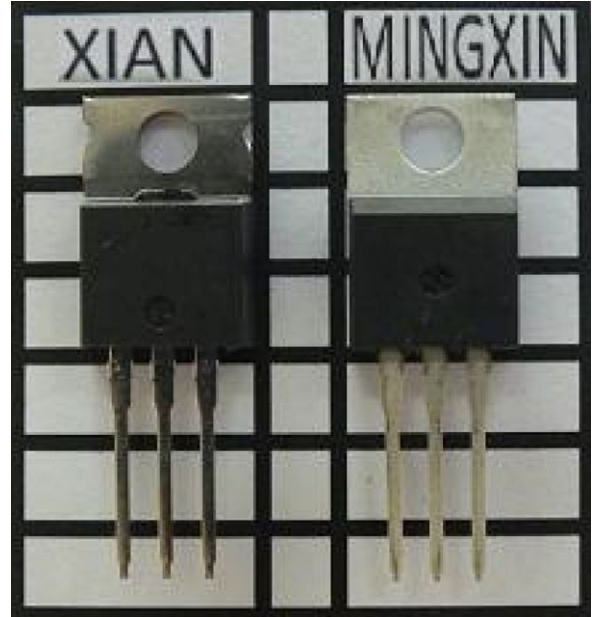


| DIM. | MILLIMETERS | | INCHES | |
|-----------------|-------------|-------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.25 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.01 | 0.027 | 0.040 |
| b(1) | 1.20 | 1.73 | 0.047 | 0.068 |
| c | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.85 | 15.49 | 0.585 | 0.610 |
| E | 10.04 | 10.51 | 0.395 | 0.414 |
| e | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.09 | 6.48 | 0.240 | 0.255 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.35 | 14.02 | 0.526 | 0.552 |
| L(1) | 3.32 | 3.82 | 0.131 | 0.150 |
| $\varnothing P$ | 3.54 | 3.94 | 0.139 | 0.155 |
| Q | 2.60 | 3.00 | 0.102 | 0.118 |

ECN: X12-0208-Rev. N, 08-Oct-12
DWG: 5471

Notes

- * M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM
- Xi'an and Mingxin actual photo





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